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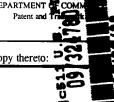
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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereto:	
Name of conveying party(ies):	2. Name and address of receiving party(ies):
Joong-Ha YOU	Name: LG Semicon Co., Ltd.
	Internal Address:
Additional name(s) of conveying party(ies) attached? _Yes X_No	
3. Nature of conveyance:	
X Assignment Merger	Street Address: 1, Hyangjeong-Dong, Hungduk-Ku
Security Agreement Change of Name	City: Cheongju
Other	State/Country: <u>Choongcheongbuk-Do, Korea</u> ZIP:
Execution Date: May 20, 1999	Additional name(s) & address(es) attached? _ Yes _ X _ No
4. Application number(s) or patent number(s):	
If the document is being filed together with a new application, the execution date of the application is: May 20, 1999	
A. Patent Application No(s).: 67/384780 Filed:	B. Patent No(s)
Additional numbers attached? Yes X No	
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: FLESHNER & KIM	7. Total fee (37 C.F.R. 3.41)\$40.00
Internal Address:	X Enclosed (Check No. 7225)
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Street Address: P. O. Box 221200	8. Deposit account number:
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9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Daniel Y.J. Kim, Reg. No. 36,186 Name and Registration No. of Person Signing Signature Total number of pages comprising cover sheet: 2 CMB No. 0851-0011 (exp. 4/94)	
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PATENT REEL: 010014 FRAME: 0823

Docket No.:	
	<u>ASSIGNMENT</u>
In consideration of the premises and other good undersigned,	and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the
(I) Joong-Ha YOU	(4)
(2)	
	(6)
who have made a certain new and useful invention, hereby se	
LG SEMICON CO., LTD.	
its successors and assigns (hereinafter designated "ASSIGNEE" entitled	") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the inventio
MEMBER FOR SEMICONDUCTOR PA	ACKAGE AND SEMICONDUCTOR PACKAGE USING THE SAME,
AND FABRICATION METHOD THEF	REOF
(a) for which an application for United States Letters Patent v	was filed on, and identified by United States Serial No; or
(b) for which an application for United States Letters Patent	
granted therefor and any and all extensions, divisions, reissue	tates Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may bes, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the try to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the tion shall hereafter act on behalf of said ASSIGNEE.
reissued or extended Letters Patent of the United States, upon re in and to any improvements, and applications for patent based	ke interest, and to render all necessary assistance in making application for and obtaining original, divisional equest of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, it also ASSIGNEE's full protection and title in and to the invention hereby transferred.
SIGNED on the dates indicated aside our signatures: INVENTORS	DATE SIGNED
Name. Joong-Ha YOU	May 20. 1999
2)Name:	<u> </u>
3)Name:	
4)Name;	
z.	

PATENT REEL: 010014 FRAME: 0824

Name: